

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	2.1 X 2.1 X 0.55
Lead Count	16
Terminal Finish	NiPdAu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.30E-03	83.25	832500	21.24	212357
Thermosets	Epoxy resin	158117-90-9 / 85954-11-6	1.50E-04	5.42	54200	1.38	13826
Thermosets	Phenol resin	26834-02-6	9.52E-05	3.45	34500	0.88	8800
Other inorganic materials	Metal Hydroxide	1309-42-8 / 20427-58-1	1.50E-04	5.42	54200	1.38	13826
Others	Others	Proprietary	6.79E-05	2.46	24600	0.63	6275
Subtotal			2.76E-03	100.00	1000000	25.51	255083

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.92 E-03	96.20	962000	54.68	546793
Copper & its alloys	Nickel	7440-02-0	1.85 E-04	3.00	30000	1.71	17052
Copper & its alloys	Silicon	7440-21-3	4.00 E-05	0.65	6500	0.37	3695
Copper & its alloys	Magnesium	7439-95-4	9.23 E-06	0.15	1500	0.09	853
Subtotal			6.15 E-03	100.00	1000000	56.84	568392

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	9.09 E-05	90.9	909091	0.84	8402
Precious metals	Palladium	7440-05-3	7.91 E-06	7.9	79051	0.07	731
Precious metals	Gold	7440-57-5	1.19 E-06	1.2	11858	0.01	110
Subtotal			1.00 E-04	100.00	1000000	0.92	9242

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.90 E-04	99.0	990000	9.150	91497
Precious Metals	Palladium	7440-05-3	1.00 E-05	1.0	10000	0.092	924
Subtotal			1.00 E-03	100.0	1000000	9.24	92421

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.10 E-04	100.0	1000000	6.56	65619

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.00 E-05	70.00	700000	0.65	6470
Other organic materials	Resin	Proprietary	1.50 E-05	15.00	150000	0.14	1386
Others	Additive	Proprietary	1.00 E-05	10.00	100000	0.09	924
Other organic materials	Bisphenol A Glycidylether	25068-38-6	5.00 E-06	5.00	50000	0.05	462
Subtotal			1.00 E-04	100.0	1000000	0.92	9242

Package Totals	Weight (g)	Percentage (%)	PPM
	1.08 E-02	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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